

Title (en)  
Thermoplastic resin composition

Title (de)  
Thermoplastische Harzzusammensetzung

Title (fr)  
Composition de résine thermoplastique

Publication  
**EP 1170335 A3 20030205 (EN)**

Application  
**EP 01116233 A 20010704**

Priority  
JP 2000204512 A 20000706

Abstract (en)  
[origin: EP1170335A2] The invention provides a thermoplastic resin composition high in mechanical strength such as flexural strength, weld strength and tensile elongation and excellent in moldability and friction property. The resin composition contains a polyamide resin component composed of 5 to 95% by weight of the following component (A) and 95 to 5% by weight of the following component (B) : Component (A): a polyamide resin obtained by polycondensing diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s) including at least adipic acid; and Component (B): a polyamide resin obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine with dicarboxylic acid(s) including at least terephthalic acid.

IPC 1-7  
**C08L 77/00**; **C08L 77/06**; **C08G 69/26**

IPC 8 full level  
**C08G 69/26** (2006.01); **C08K 3/00** (2006.01); **C08L 77/00** (2006.01); **C08L 77/06** (2006.01); **H01L 23/29** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP US)  
**C08G 69/26** (2013.01 - EP US); **C08L 77/00** (2013.01 - EP US); **C08L 77/06** (2013.01 - EP US)

Citation (search report)

- [Y] US 4716214 A 19871229 - GAYMANS REINOUD J [NL], et al
- [Y] EP 0976774 A2 20000202 - KURARAY CO [JP]
- [Y] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 05 30 May 1997 (1997-05-30)

Cited by  
CN102311641A; EP2431419A1; CN103635537A; RU2645353C1; US10377897B2; US7166243B2; US7132063B2; WO2005017042A1; WO2005017039A1; WO2015177092A1; US9181429B2; US10577500B2; US7118691B2; US7182886B2; US8858839B2; WO2005017041A1; WO2005017040A1; WO2012175293A1; WO2015197124A1

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**EP 01116233 A 20010704**; DE 60134193 T 20010704; JP 2000204512 A 20000706; US 88625601 A 20010622